

FABRICATIONS NOTES

- 1. MATERIAL
 FR4 LAYERS: 2 CU: 10Z
 TICKNESS: 1,6 mm
- 2. SUFACE FINISH
 SELECTIVE SN PB
- 3. SOLDERMASK
 SOLDERMASK OVER BARE COPPER
 LIQUID PHOTO-IMAGEABLE (LPI)
 TOP COLOR: GREEN
 BOTTOM COLOR: GREEN
- 4. SILKSCREEN
 EPOXY NON CONDUCTIVE
 TOP COLOR: WHITE
 BOTTOM COLOR: WHITE
- 5. PACKAGING REQUIREMENTS
 PACKAGED IN VACUUM SEALED INNER CONTAINERS

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,036mm		
4	Dielectric 1	FR-4	1,500mm	4,8	
5	Bottom Layer	Copper	0,036mm		
6	Bottom Solder	Solder Resist	O,010mm	3,5	
7	Bottom Overlay				

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DRAWN	Luciano Aguerre	14.05.2021	TOLERANCES UNLESS OTHERWISE NOTED	
CHECKED				
APPROVED			LINEAR 0,2mm	
APPROVED			ANGULAR 1	

TITLE
MODULO DE TESTEO PARA BURN IN

DWG SIZE	PART N# TEST-1	REV	
П3	SCALE 1:1	SHEET 1 OF 1	H